IXYS

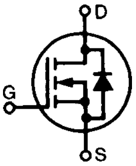
HiPerFET™ Power MOSFETs

	V_{DSS}	I_{D25}	$R_{DS(on)}$
IXFH/~~IXFM~~6N90	**900 V**	**6 A**	**1.8 Ω**
IXFH/~~IXFM~~6N100	**1000 V**	**6 A**	**2.0 Ω**

$t_{rr} \leq 250$ ns

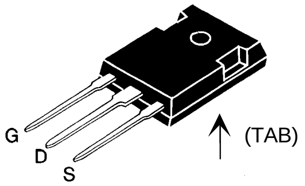
N-Channel Enhancement Mode
High dv/dt, Low t_{rr}, HDMOS™ Family

Obsolete:
IXFM6N90
IXFM6N100



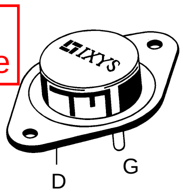
Symbol	**Test Conditions**		**Maximum Ratings**	
V_{DSS}	T_J = 25°C to 150°C	6N90	900	V
V_{DGR}	T_J = 25°C to 150°C; R_{GS} = 1 MΩ	6N100	1000	V
V_{GS}	Continuous		±20	V
V_{GSM}	Transient		±30	V
I_{D25}	T_C = 25°C		6	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}		24	A
I_{AR}	T_C = 25°C		6	A
E_{AR}	T_C = 25°C		18	mJ
dv/dt	$I_S \leq I_{DM}$, di/dt ≤ 100 A/µs, $V_{DD} \leq V_{DSS}$, $T_J \leq 150$°C, R_G = 2 Ω		5	V/ns
P_D	T_C = 25°C		180	W
T_J			-55 ... +150	°C
T_{JM}			150	°C
T_{stg}			-55 ... +150	°C
T_L	1.6 mm (0.062 in.) from case for 10 s		300	°C
M_d	Mounting torque		1.13/10	Nm/lb.in.
Weight			TO-204 = 18 g, TO-247 = 6 g	

TO-247 AD (IXFH)



~~**TO-204 AA (IXFM)**~~

Package unavailable



G = Gate, D = Drain,
S = Source, TAB = Drain

Features

- International standard packages
- Low $R_{DS\ (on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect
- Fast intrinsic Rectifier

Symbol	**Test Conditions**		**Characteristic Values** (T_J = 25°C, unless otherwise specified) **min.**	**typ.**	**max.**	
V_{DSS}	V_{GS} = 0 V, I_D = 3 mA	6N90	900			V
		6N100	1000			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 2.5 mA		2.0		4.5	V
I_{GSS}	V_{GS} = ±20 V_{DC}, V_{DS} = 0				±100	nA
I_{DSS}	V_{DS} = 0.8 • V_{DSS}	T_J = 25°C			250	µA
	V_{GS} = 0 V	T_J = 125°C			1	mA
$R_{DS(on)}$	V_{GS} = 10 V, I_D = 0.5 • I_{D25}	6N90			1.8	Ω
		6N100			2.0	Ω
	Pulse test, t ≤ 300 µs, duty cycle d ≤ 2 %					

Applications

- DC-DC converters
- Synchronous rectification
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control
- Temperature and lighting controls
- Low voltage relays

Advantages

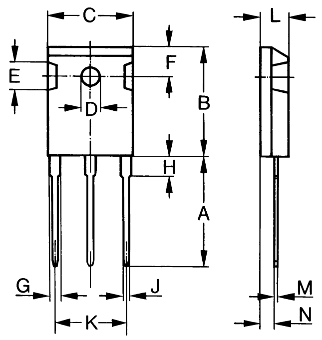
- Easy to mount with 1 screw (TO-247) (isolated mounting screw hole)
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
g_{fs}	V_{DS} = 10 V; I_D = 0.5 • I_{D25}, pulse test	4	6		S
C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		2600		pF
C_{oss}			180		pF
C_{rss}			45		pF
$t_{d(on)}$	V_{GS} = 10 V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25} R_G = 4.7 Ω (External)		35	100	ns
t_r			40	110	ns
$t_{d(off)}$			100	200	ns
t_f			60	100	ns
$Q_{g(on)}$	V_{GS} = 10 V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		88	130	nC
Q_{gs}			21	30	nC
Q_{gd}			38	70	nC
R_{thJC}				0.7	K/W
R_{thCK}			0.25		K/W

Source-Drain Diode

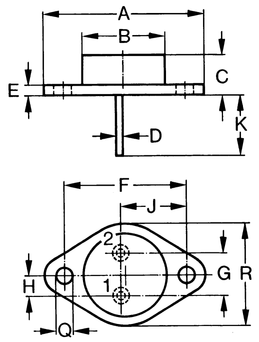
Symbol	Test Conditions		Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
I_S	V_{GS} = 0 V				6	A
I_{SM}	Repetitive; pulse width limited by T_{JM}				24	A
V_{SD}	$I_F = I_S$, V_{GS} = 0 V, Pulse test, t ≤ 300 µs, duty cycle d ≤ 2 %				1.5	V
t_{rr}	$I_F = I_S$ -di/dt = 100 A/µs, V_R = 100 V	T_J = 25°C			250	ns
		T_J = 125°C			400	ns
Q_{RM}		T_J = 25°C		0.5		µC
		T_J = 125°C		1.0		µC
I_{RM}		T_J = 25°C		7.5		A
		T_J = 125°C		9.0		A

TO-247 AD (IXFH) Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

TO-204 AA (IXFM) Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	38.61	39.12	1.520	1.540
B	19.43	19.94	-	0.785
C	6.40	9.14	0.252	0.360
D	0.97	1.09	0.038	0.043
E	1.53	2.92	0.060	0.115
F	30.15	BSC	1.187	BSC
G	10.67	11.17	0.420	0.440
H	5.21	5.71	0.205	0.225
J	16.64	17.14	0.655	0.675
K	11.18	12.19	0.440	0.480
Q	3.84	4.19	0.151	0.165
R	25.16	25.90	0.991	1.020

IXYS MOSFETS and IGBTs are covered by one or more of the following U.S. patents:
4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025

Fig. 1 Output Characteristics

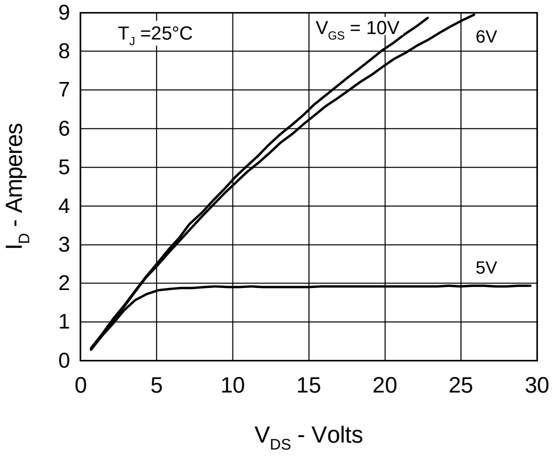


Fig. 2 Input Admittance

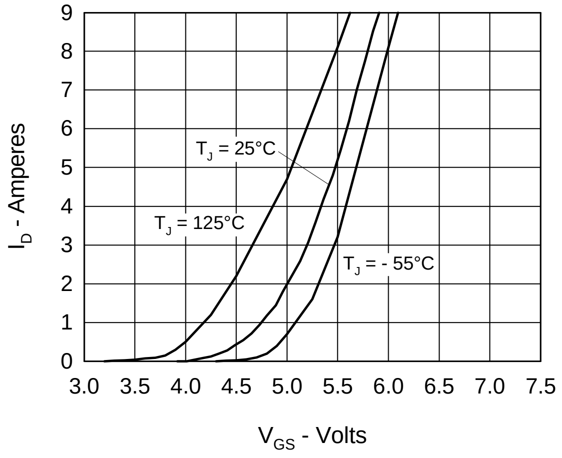


Fig. 3 $R_{DS(on)}$ vs. Drain Current

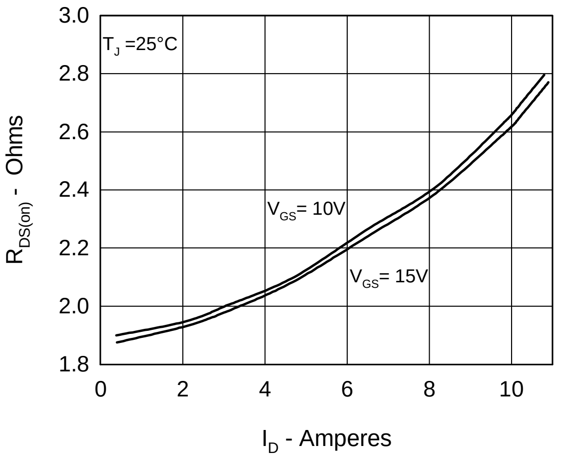


Fig. 4 Temperature Dependence of Drain to Source Resistance

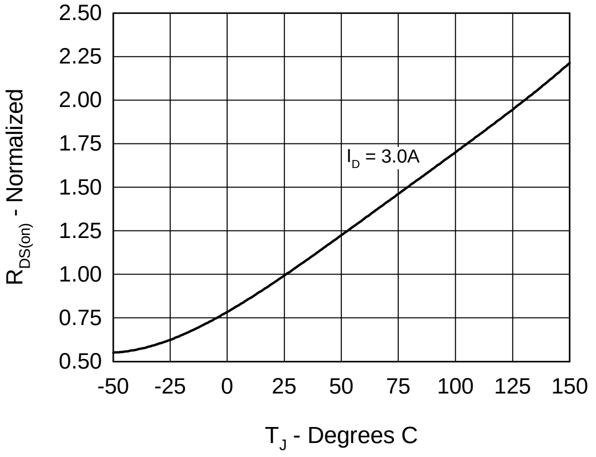


Fig. 5 Drain Current vs. Case Temperature

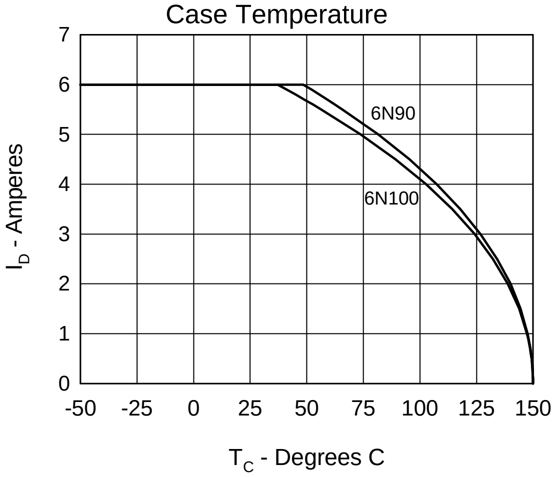


Fig. 6 Temperature Dependence of Breakdown and Threshold Voltage

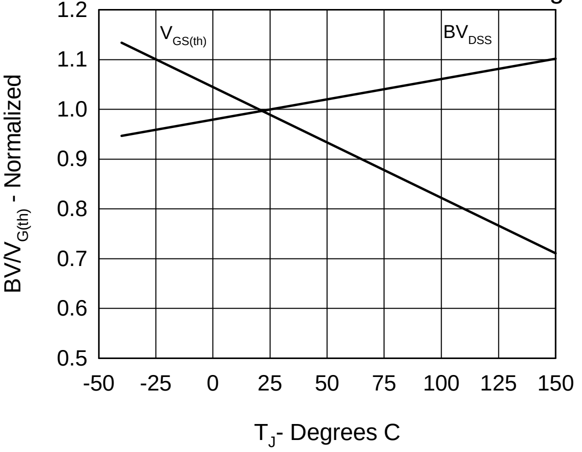


Fig.7 Gate Charge Characteristic Curve

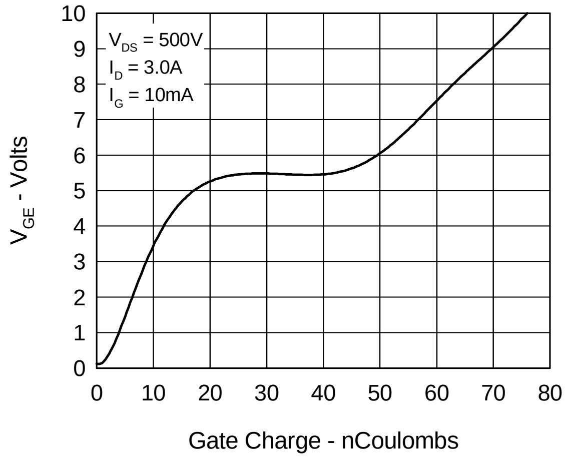


Fig.8 Forward Bias Safe Operating Area

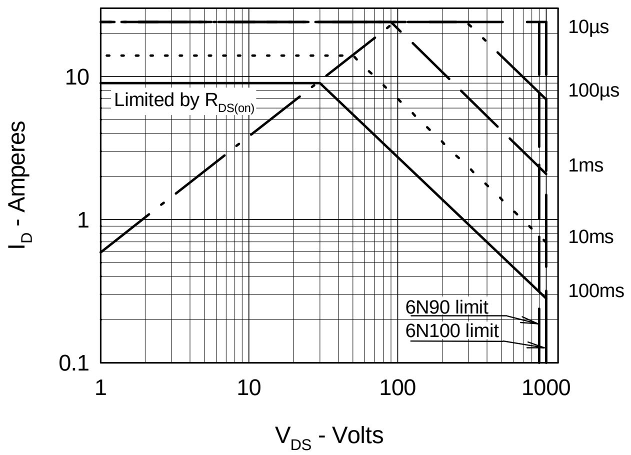


Fig.9 Capacitance Curves

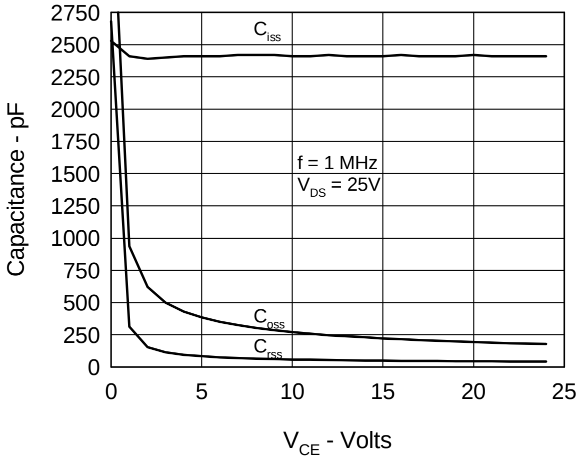


Fig.10Source Current vs. Source to Drain Voltage

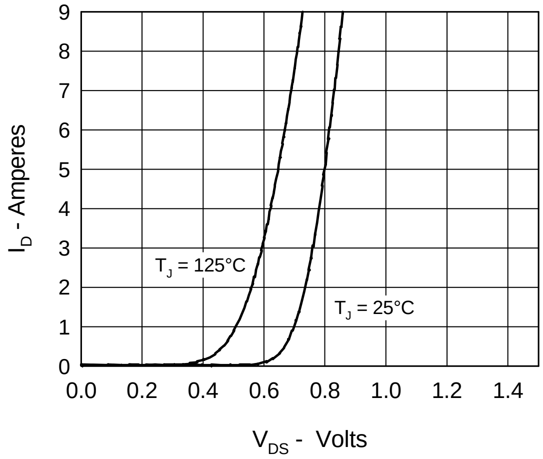
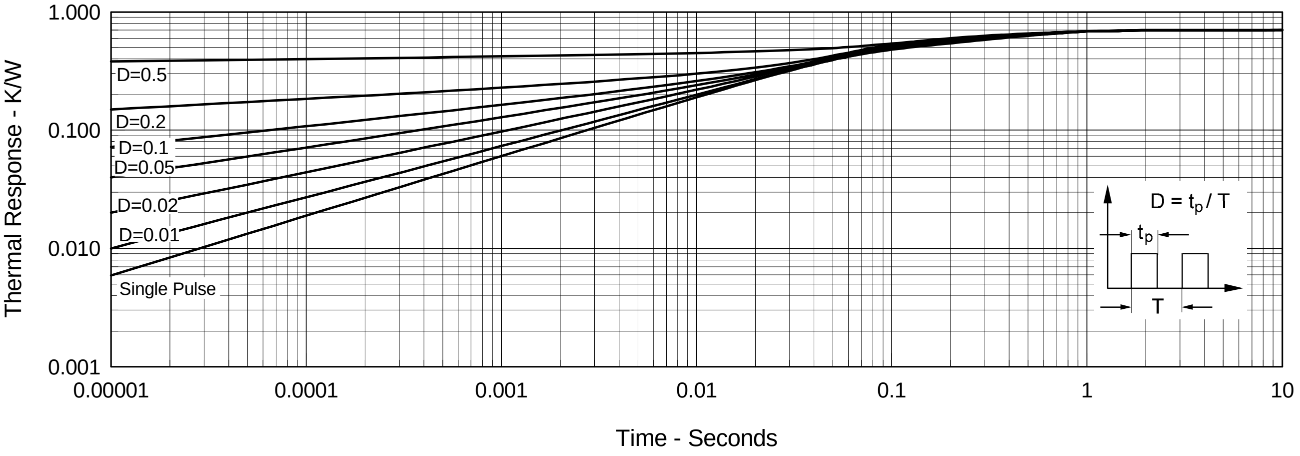


Fig.11 Transient Thermal Impedance



IXYS

A Littelfuse Technology
